

# SOT1129-2

plastic ball grid array package; 324 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA324
<b>Package type industry code</b>	BGA324
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	31-3-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	2.05	-	2.23	2.4	mm
A <sub>2</sub>	package height	1.65	-	1.73	1.8	mm
e	nominal pitch	-	-	1	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	324	-	



## 2. Package outline

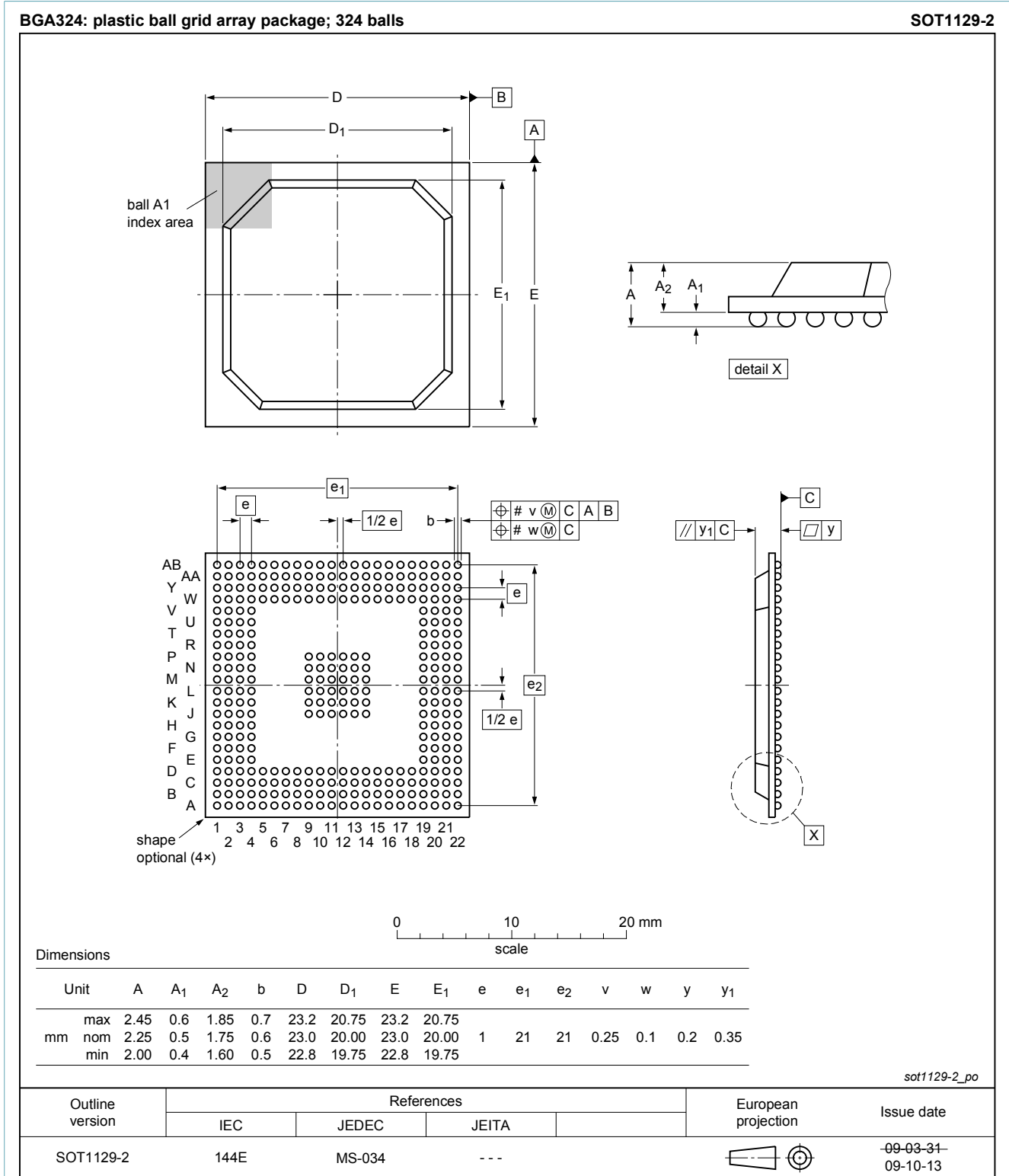


Fig. 1. Package outline BGA324 (SOT1129-2)

### 3. Legal information

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